



PC Board Layout
Component Side Shown

MECHANICAL

1. SHIELD MATERIAL : CARTRIDGE $t=0.25\text{mm}$.
10U"-20U" THICK NICKEL OVER 10U"-20U" MIN.
THICK NICKEL.
Tinned grounding tab, $H=2.00\text{mm}$ (Min), $W=2.10\text{mm}$ (Max).
2. HOUSING MATERIAL: PBT+30%GF. THERMOPLASTIC UL94V-0;
3. INSERT MATERIAL: PBT+30%GF. THERMOPLASTIC UL94V-0;
4. CONTACT MATERIAL : PHOSPHORUS BRONZE $t=0.35\text{mm}$. (C5210EH)
5. PLATING : 1. MATING AREA- 3u" MIN. GOLD OVER 30-80u" BRIGHT NICKEL.
2. SOLDER AREA- 75-300u" TIN-LEAD OVER 30-80u" NICKEL.
3. LED PINS AREA- 75-300u" TIN-LEAD OVER 30-80u" NICKEL.

REV	ECN NO	DESCRIPTION	DATE	Jions 北京玖恩启明电子科技有限公司						UNITS:	SCALE:	DWG NO:	SHEET:10/1
A	JIONS-SATYA-0001		2013/01/21							mm	1:1	WWW.JIONS.COM.CN	REV:

X	±0.30	APPR:	Mr.wu	TITLE:
XX	±0.20	CHKD:	Mr.wu	双层USB母座+单网口 带灯
XXX	±0.05	Dr:	Gus chong	PART No: JIONS-0043
X'	±1"			